

FOR: BE SEMICONDUCTOR INDUSTRIES N.V.
Ratio 6
6921 RW Duiven
The Netherlands

PRESS RELEASE

BE Semiconductor Industries Announces RFID Die Bonding Equipment Orders

Duiven, the Netherlands, March 31, 2008, BE Semiconductor Industries N.V. ("the Company" or "Besi") (Euronext: BESI), a leading manufacturer of assembly equipment for the semiconductor industry, today announced the receipt in March of orders and letters of intent aggregating approximately US\$ 4.4 million for RFID die bonding equipment.

Besi's Datacon subsidiary received orders recently aggregating US\$ 2.8 million and additional letters of intent of US\$ 1.6 million for its 8800 FC ("Flip Chip") Smart Line die bonding system. The 8800 FC Smart Line system is a fully automated, high-performance production line providing customers a complete Radio Frequency Identification Device ("RFID") chip assembly solution based on a highly cost-effective method of direct chip attach to RFID antennae. The firm orders for four systems were placed by two European manufacturers of RFID tags and are anticipated to be delivered primarily in the second quarter of 2008. The letters of intent for two systems were received from one Asian and one European manufacturer of RFID tags for delivery in the third quarter of 2008.

Helmut Rutterschmidt, Executive Board member and Head of Marketing and Sales of Besi commented, "We are very pleased to receive these important customer orders and letters of intent this month reflecting our increased penetration and market share of the European and Asian RFID tag markets by our Smart Line systems in direct, head to head competition."

About BE Semiconductor Industries N.V.

BE Semiconductor Industries N.V. designs, develops, manufactures, markets and services die sorting, flip chip and multi-chip die bonding, packaging and plating equipment for the semiconductor industry's assembly operations. Its customers consist primarily of leading U.S., European and Asian semiconductor manufacturers, assembly subcontractors and electronics and industrial companies which utilize its products for both array connect and conventional leadframe manufacturing processes. For more information about Besi, please visit our website at www.besi.com.

Caution Concerning Forward Looking Statements

This press release contains forward-looking statements, which are found in various places throughout the press release, including statements relating to expectations of orders, net sales, product shipments, backlog, timing of purchases of assembly equipment by customers and capital expenditures. The words “anticipate”, “estimate”, “expect”, “can”, “intend”, “believes”, “may”, “plan”, “predict”, “project”, “forecast”, “will”, “would”, and similar expressions are intended to identify forward looking statements, although not all forward looking statements contain these identifying words. While these forward looking statements represent our judgments and future expectations concerning the development of our business, a number of risks, uncertainties and other important factors could cause actual developments and results to differ materially from our expectations. These factors include, but are not limited to, those listed or discussed in Besi’s Annual Report for the year ended December 31, 2006, as well as the risk that anticipated orders may not materialize or that orders received may be postponed or canceled, generally without charges; the volatility in the demand for semiconductors and our products and services; acts of terrorism and violence; overall global economic conditions; risks, such as changes in trade regulations, currency fluctuations, political instability and war, associated with substantial foreign customers, suppliers and foreign manufacturing operations; potential instability in foreign capital markets; the risk of failure to successfully manage our expanding and more diverse operations; and other key factors that could adversely affect our businesses and financial performance contained in our filings and reports, including our statutory consolidated statements. We are under no obligation to (and expressly disclaim any such obligation to) update or alter our forward-looking statements whether as a result of new information, future events or otherwise.

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PERSBERICHT

BE Semiconductor Industries kondigt orders aan voor RFID die bonding machines

Duiven, 31 maart 2008, BE Semiconductor Industries N.V. ("Besi") (Euronext: BESI), een toonaangevende leverancier van machines voor de assemblage van halfgeleiders maakt melding van de ontvangst in maart 2008 van orders en LOI's voor die bonding machines voor een totaalbedrag van US\$ 4,4 mio.

Besi dochter Datacon heeft twee orders ontvangen voor een totaalbedrag van US\$ 2,8 mio en twee LOI's voor US\$ 1,6 mio voor 8800 FC ("Flip Chip") Smart Line die bonding machines. De 8800 FC Smart Line is een geautomatiseerde "high-performance" productielijn voor Radio Frequency Identification Device ("RFID") chipmontage gebaseerd op een lage kostenmethode voor het rechtstreeks plaatsen van chips op RFID antennes. De orders voor vier productielijnen zijn afkomstig van twee Europese producenten van RFID tags en staan gepland voor uitlevering in Q2-2008. De LOI's voor twee productielijnen zijn geplaatst door een Aziatische en een Europese producent van RFID tags voor geplande levering in Q3-2008.

Helmut Rutterschmidt, Raad van Bestuurslid Marketing & Sales Besi: "Wij zijn zeer verheugd met deze belangrijke orders en LOI's, welke een bewijs zijn voor een groeiend marktaandeel in Europa en Azië van Datacon die bonding machines voor RFID".

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